

Title (en)  
Process for manufacturing a flooring panel

Title (de)  
Verfahren zum Herstellen eines Fussbodenpaneels

Title (fr)  
Procédé de fabrication d'un panneau de plancher

Publication  
**EP 1719596 A1 20061108 (DE)**

Application  
**EP 05009850 A 20050504**

Priority  
EP 05009850 A 20050504

Abstract (en)  
The method involves having a core consisting of a fiber material, preferably MDF- or HDF plate. One part of the panel (1) is cut by laser. The laser cut partly runs by a core (4) made of synthetic material. A layer (3) containing a panel (2) has the laser cut providing an edge. The laser cut runs by the layer and partly into the core. An independent claim is included for a floor board.

IPC 8 full level  
**B27M 3/04** (2006.01); **B27M 1/08** (2006.01); **E04F 15/02** (2006.01)

CPC (source: EP US)  
**B27M 1/08** (2013.01 - EP US); **B27M 3/04** (2013.01 - EP US); **E04F 15/02038** (2013.01 - EP US); **E04F 15/04** (2013.01 - EP US); **E04F 2201/0115** (2013.01 - EP US); **E04F 2201/026** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)  
AL BA HR LV MK YU

DOCDB simple family (publication)  
**EP 1719596 A1 20061108; EP 1719596 B1 20081224**; AT E418431 T1 20090115; CA 2587378 A1 20061109; CA 2587378 C 20160119; CN 101171111 A 20080430; CY 1108943 T1 20140702; DE 502005006323 D1 20090205; DK 1719596 T3 20090420; ES 2320352 T3 20090521; PL 1719596 T3 20090630; PT 1719596 E 20090401; SI 1719596 T1 20090630; US 2009101236 A1 20090423; US 8082959 B2 20111227; WO 2006117229 A1 20061109

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